



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 THICKNESS: 1.4L [0.55] MIN
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD

RECOMMENDED PANEL CUTOUT

REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
A		REV PER ECOSI 1-0201-04	PLM/MS	AT	SF
A1		ADDED NEW DASH NUMBER -3	PLM/MS	DZ	MS
A2		REVISED	PLM/MS	DZ	MS

- △ THERMOPLASTIC, COLOR-BLACK.
- △ PHOSPHOR BRONZE
- △ 1.27mm [0.00050] MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2um [0.000093] MIN MATTE TIN ON TERMINATION END, BOTH OVER 1.27mm [0.00050] MIN NICKEL.
- △ CAVITY CONFORMS TO FCC 47 CFR 68 PART F.
- △ DATUMS ESTABLISHED BY CUSTOMER.
- △ DIMENSIONS ESTABLISHED BY CUSTOMER.
- △ DRILLED HOLE DIAMETER 1.02±0.031 [0.040.001]. COPPER THK 0.03±0.001 [0.001-.002]. TIN THICKNESS 8um [0.00315] MIN.
- △ PC BOARDS GREATER THAN 1.57L [0.62] IN THICKNESS MAY REQUIRE SPECIAL EXTRACTION TOOLING, CONSULT ENGINEERING.

NO 'AMP' LOGO, NO PIN 5 & 6	6116201-3
NO 'AMP' LOGO	6116201-2
AS SHOWN	6116201-1
DESCRIPTION	PART NUMBER

TFCB Electronics
 Harrisburg, PA 17105-3600
 MODULAR JACK ASSEMBLY
 VERTICAL COMPLIANT PIN, B POSITION,
 CATEGORY 5
 DATE: 07-13-2005
 DRAWING NO: 6116201-3
 CUSTOMER DRAWING